

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4076544

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MING-YEN CHIU	09/22/2016
CHING-FU CHANG	09/23/2016
CHIEN-CHIA CHIU	09/22/2016
HSIN-CHIEH HUANG	09/23/2016
TSUNG-SHU LIN	09/22/2016
PEI-TI YU	09/23/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
<b>Street Address:</b>	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15281043
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(510)580-7280
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	USA@JCIPGROUP.COM
<b>Correspondent Name:</b>	JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE
<b>Address Line 1:</b>	7 FLOOR-1, NO. 100
<b>Address Line 2:</b>	ROOSEVELT ROAD, SECTION 2
<b>Address Line 4:</b>	TAIPEI, TAIWAN 100
<b>ATTORNEY DOCKET NUMBER:</b>	63244-US-PA
<b>NAME OF SUBMITTER:</b>	BELINDA LEE
<b>SIGNATURE:</b>	/Belinda Lee/
<b>DATE SIGNED:</b>	09/29/2016
<b>Total Attachments: 3</b>	

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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Declaration Submitted With Initial Filing

OR

Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**CONDUCTIVE PATTERN AND INTEGRATED FAN-OUT PACKAGE  
HAVING THE SAME**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

The attached application,

OR

United States Application Number or PCT International application number \_\_\_\_\_

Filed on \_\_\_\_\_.

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. Taiwan Semiconductor Manufacturing Co., Ltd.  
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,  
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Ming-Yen Chiu Date: 2016.09.22

Legal Name of Sole or First Inventor: Ming-Yen Chiu

Residence: Hsinchu County, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Ching-Fu Chang Date: 2016.9.23

Legal Name of Additional Joint Inventor, if any: Ching-Fu Chang

Residence: Taipei City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chien-Chia Chiu Date: 2016.9.22

Legal Name of Additional Joint Inventor, if any: Chien-Chia Chiu

Residence: Taoyuan City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Hsin-Chieh Huang Date: 2016.9.23

Legal Name of Additional Joint Inventor, if any: Hsin-Chieh Huang

Residence: Hsin-Chu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Tsung-Shu Lin Date: 2016.9.22

Legal Name of Additional Joint Inventor, if any: Tsung-Shu Lin

Residence: New Taipei City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Pei-Ti Yu Date: 2016.9.23

Legal Name of Additional Joint Inventor, if any: Pei-Ti Yu

Residence: Taipei, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.